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IN THE CLAIMS

Claims 1-15 (cancelled)

Claim 16 (withdrawn)

Claim 17 (cancelled)

Claim 18 (previously presented): A method of manufacturing a flex circuit on a flexible base polymer film including the steps of:

- a) superimposing on said film an embossing tool having raised areas comprising a pattern of conductors and vias corresponding to a circuit design, wherein, said raised areas are coated with a thin layer of metal, comprising copper,
- b) applying heat and pressure to simultaneously emboss the film and to transfer said thin metal layer from the embossing tool to the polymer film,
- c) removing the embossing tool,
- d) embossing a pattern corresponding to that of the second surface of a flex circuit, and simultaneously transferring a thin layer of metal into the embossed pattern,
- e) physically removing the embossing tool,
- f) plating a layer of copper to fill the vias and conductor patterns on both sides of the film,
- g) plating a layer of nickel and gold onto the exposed copper patterns, and
- h) applying a solder mask on the surface of the film surrounding the solder ball contact pads.

Claims 19 and 20 (cancelled)

Claim 21 (currently amended): A method of manufacturing a flex circuit on a flexible base polymer film including the steps of:

- a) positioning adjacent to said film an a single embossing tool having raised areas comprising a pattern of conductors and vias corresponding to a circuit design, wherein said raised areas are coated with a thin layer of metal;
- b) applying heat and pressure on said tool to simultaneously emboss the film and to transfer said thin metal layer from the embossing tool to the polymer film; and
- c) plating a second layer of metal on said transferred thin metal layer.

Claim 22 (previously presented): The method of Claim 21, wherein said thin layer of metal is copper.

Claim 23 (previously presented): The method of Claim 21, wherein said second layer of metal is copper.

Claim 24 (previously presented): The method of Claim 21, comprising the step of plating at least one additional layer on said second layer of metal.

Claim 25 (previously presented): The method of Claim 21, wherein said steps a), b) and c) are performed on two surfaces of said film.